

## ABSTRACT OF THE DISCLOSURE

[0049] The present invention provides an adhesion method of improving the heat conduction in a fixed direction by using a heat conductive adhesive made by blending boron nitride powder and adhesive polymer and adhering by orienting boron nitride powder in the heat  
10 conductive adhesive to the fixed direction under the magnetic atmosphere and an electronic component for effectively dissipating heat generated from semiconductor device 2, power source 4, light source or other components used for the electric products, and an electronic component excellent in radiation.